

PH5553A2NA1

Ambient Light Sensor

Data Sheet R08DS0068EJ0100 Rev.1.00 Nov 07, 2012

DESCRIPTION

The PH5553A2NA1 is a digital ambient light sensor for I^2C bus interfaces and includes a 16-bit AD converter. This product has spectral characteristics close to human eye sensitivity and outputs digital signals corresponding to the ambient brightness.

The PH5553A2NA1 can be used to improve the performance and reduce the power consumption of digital equipment such as FPD TV sets and mobile phones, by enabling automatic brightness control and automatic switching on and off of lighting systems.

FEATURES

- Small and thin SON package 2.55 x 1.56 x 0.55 mm
- Built-in 16-bit AD converter
- I²C bus interface 1.8 V reference supply voltage
- Spectral characteristics close to human eye sensitivity Peak sensitivity wavelength 550 nm TYP.
- Light source dependence with mounting the device can be reduced by the spectral characteristics adjustment function from visible region to infrared region.
- The calculation after illuminance output is not necessary by selecting the spectral characteristics from 16 patterns of those.
- Illuminance detection of wide region can be realized.

Minimum detectable illuminance0.1 lxMaximum detectable illuminance65 535 lx

Pb-free

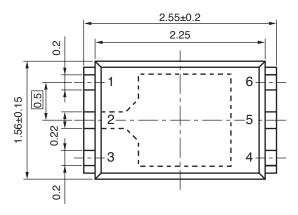
APPLICATIONS

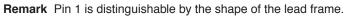
- FPD TV sets, displays
- Mobile phones, smartphones
- Notebook PCs, tablet PCs
- DSCs, DVCs
- FA equipment
- · Lighting systems, etc.

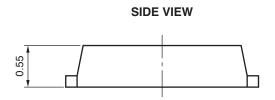


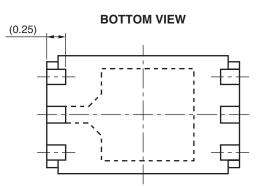
PACKAGE DIMENSIONS (UNIT: mm)

TOP VIEW









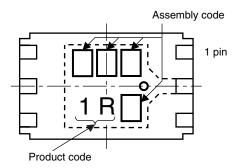
Remark () indicates nominal dimensions.

Pin No.	Terminal	I/O	Function
1	V _{DD}	-	Supply Voltage
2	GND	-	GND
3	V _{IO}	-	I ² C bus interface reference supply voltage
4	SCL	I	I ² C bus SCL
5	TEST	-	Test (Be sure to connect to GND.)
6	SDA	10	I ² C bus SDA



MARKING

(Bottom View)



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style
PH5553A2NA1-E4	PH5553A2NA1-E4-Y-A	Pb-Free	Embossed Tape 5 000 pcs/reel

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD}	4.5	V
I ² C Reference Voltage	V _{IO}	V _{DD}	V
Power Dissipation ^{*1}	PD	135	mW
Operating Temperature	T _A	-30 to +85	°C
Storage Temperature	T _{stg}	-40 to +100	°C

Note: *1. Mounted on glass epoxy board (18 mm \times 13 mm \times ^t0.8 mm)

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{DD}	2.4	3.0	3.6	V
I ² C Reference Voltage	V _{IO}	1.65	_	V_{DD}	V



ELECTRO-OPTICAL CHARACTERISTICS ($T_A = 25^{\circ}C$, $V_{DD} = 3.0$ V, $V_{IO} = 1.8$ V, unless otherwise specified)

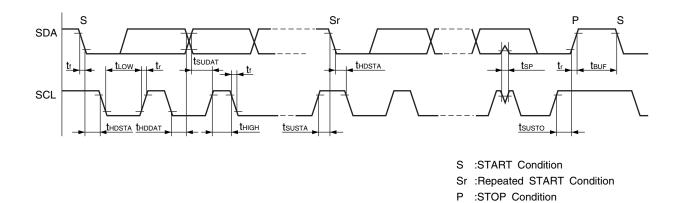
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Supply Current 1	I _{DD1}	$Ev = 100 \text{ lx}^{*1}$		130	290	μA
Supply Current 2	I _{DD2}	Ev = 100 lx ^{*1} , power-down		0.01	1	μA
Peak Sensitivity Wavelength	λρ	PD bit = "1000"		550		nm
Dark Sensor Output	_	Ev = 0 lx, PD bit = "1000", GCSW bit = 1			4	count
Illuminance Count	_	Ev = 1 000 lx ^{*1} , PD bit = "1000", GCSW bit = 1	700	1 000	1 300	count
Multiplying Factor of Illuminance Count (× 1)	GCL	PD bit = "1000", GCSW bit = 1, RSLTN bit = 0		1		count/lx
Multiplying Factor of Illuminance Count (× 10)	GCL	PD bit = "1000", GCSW bit = 0, RSLTN bit = 0		10		count/lx
H-Resolution Mode Resolution	HRM	GCSW bit = 1, RSLTN bit = 0		1		count
L-Resolution Mode Resolution	LRM	GCSW bit = 1, RSLTN bit = 1		16		count
Measurement Time in H-Resolution Mode	HRt	RSLTN bit = 0		330	495	ms
Measurement Time in L-Resolution Mode	LRt	RSLTN bit = 1		21	32	ms
I ² C SCL Clock Frequency	f _{SCL}				400	kHz
I ² C Bus Free Time	t _{BUF}		1.3			μS
I ² C Hold Time for START Condition	t _{HDSTA}		0.6			μS
I ² C Set-up Time for START Condition	t _{SUSTA}		0.6			μS
I ² C Set-up Time for STOP Condition	tsusтo		0.6			μS
I ² C Data Hold Time	t _{HDDAT}		0		0.9	μs
I ² C Data Set-up Time	t _{SUDAT}		100			ns
I ² C 'L' Period of the SCL Clock	t _{LOW}		1.3			μS
I ² C 'H' Period of the SCL Clock	t _{HIGH}		0.6			μS
I ² C 'L' Output Voltage 1 at SDA	V _{OL1}	$V_{IO} > 2V, I_{IO} = 3mA$	0		0.4	V
I ² C 'L' Output Voltage 2 at SDA	V _{OL2}	$V_{IO} \le 2V, I_{IO} = 2mA$	0		0.2 x V _{IO}	V
I ² C 'L' Input Voltage at SCL, SDA	VIL		-0.5		0.3 x V _{IO}	V
I ² C 'H' Input Voltage at SCL, SDA	V _{IH}		0.7 x V _{IO}	_	V _{IO}	V

Note: *1 Fluorescent light



I²C BUS INTERFACE SPECIFICATION

1. I²C Bus Interface Timing Chart

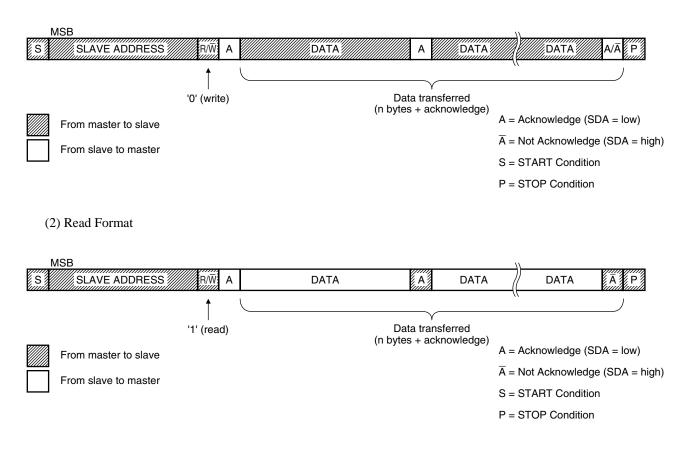


2. Slave Address

"1100100".

3. I²C Protocols

(1) Write Format





REGISTER MAP

- 1. Set values with Write operation
 - (a) Register1

· .	U								-
	0	0	0	0	0	0	0	0	default
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
	Timemanu	Register	Address	SWRST	STOP	RSLTN	GCSW	PWR	

(b) Register2

0	0	0	0	1	0	0	0	default
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	
0 (fixed)	Reserved	Reserved	Reserved	PD4	PD3	PD2	PD1	

1) Timemanu	: Measurement time manual set (1: Enable measurement time set by Register3 and Register4)
2) Register Address	: Register address set during read operation
3) SWRST	: Register reset (Initial values are restored by setting this bit to 1.)
4) STOP	: Stops lux measurement after the current ADC cycle. The lux data measured last is retained.
	The ADC enters standby mode (1: Stop)
5) RSLTN	: Illuminance count resolution selection (1: 16 count resolution, 0: 1 count resolution)
6) GCSW	: Illuminance count gain selection (1: 1 count/lx, 0: 10 count/lx)
7) PWR	: Power control switch (1: Power on, 0: Power off (standby state))
8) PD1 to PD4	: Spectral characteristics adjustment

Set values with Write Operation (Control with 4 Byte Unit (When Timemanu = 1))
When Timemanu = 1, measurement time is enabled to be changed by transferring Register1 and Register2 followed by Register3 and Register4.

(a) Register3 (when RSLTN = 0)

[0	1	0	1	0	0	0	0	default
ĺ	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
ĺ	Illuminance measurement time counter 0H in H-Resolution mode lower 8 bit (when RSLTN = 0)								

(b) Register4 (when RSLTN = 0)

	1	1	0	0	0	0	1	1	default
ĺ	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	
	Illuminan	ce measurer	nent time cou	Inter 1H in H-	Resolution m	node upper 8	bit (when RS	SLTN = 0)	

(c) Register3 (when RSLTN = 1)

0	0	1	1	0	1	0	1	default	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Illuminar	Illuminance measurement time counter 2H in L-Resolution mode lower 8 bit (when RSLTN = 1)								

(d) Register4 (when RSLTN = 1)

0	0	0	0	1	1	0	0	default
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	
Illuminance measurement time counter 3H in L-Resolution mode upper 8 bit (when RSLTN = 1)								

Method for obtaining measurement time

Measurement time (ms) = Set value / 600×4



3. Return Value during Read Operation (When Register Address = 00)

0	0	0	0	0	0	0	0	default
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Illuminance count measurements Upper 8bits								

0	0	0	0	0	0	0	0	default
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	
Illuminance count measurements Upper 8bits								1

4. Return Value during Read Operation (When Register Address = 01)

0	0	0	0	0	0	0	0	default
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Timemanu	Register	Address	SWRST	STOP	RSLTN	GCSW	PWR	
0	0	0	0	1	0	0	0	default
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	
0 (fixed)	Reserved	Reserved	Reserved	PD4	PD3	PD2	PD1	

5. Return Value during Read Operation (When Register Address = 10)

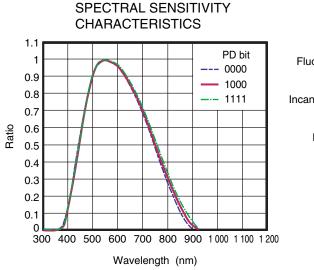
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Illuminance measurement time counter 0H in H-Resolution mode lower 8 bit (when RSLTN = 0)							
Illuminance measurement time counter 2H in L-Resolution mode lower 8 bit (when RSLTN = 1)							

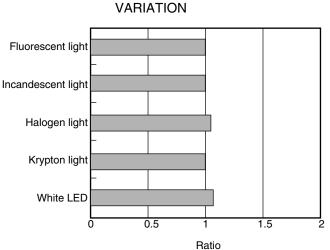
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	
Illuminance measurement time counter 1H in H-Resolution mode upper 8 bit (when RSLTN = 0)								
Illuminan	Illuminance measurement time counter 3H in L-Resolution mode upper 8 bit (when RSLTN = 1)							



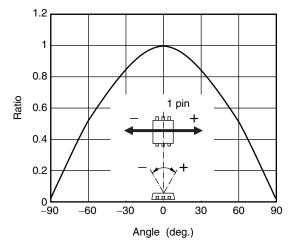
LIGHT SOURCE SENSITIVITY

TYPICAL CHARACTERISTICS (T_A = 25°C, V_{DD} = 3.0 V, V_{IO} = 1.8 V, unless otherwise specified)



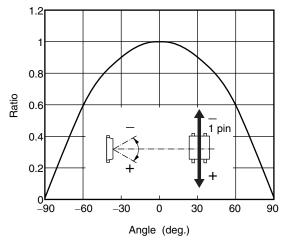


DIRECTIONAL CHARACTERISTICS 1

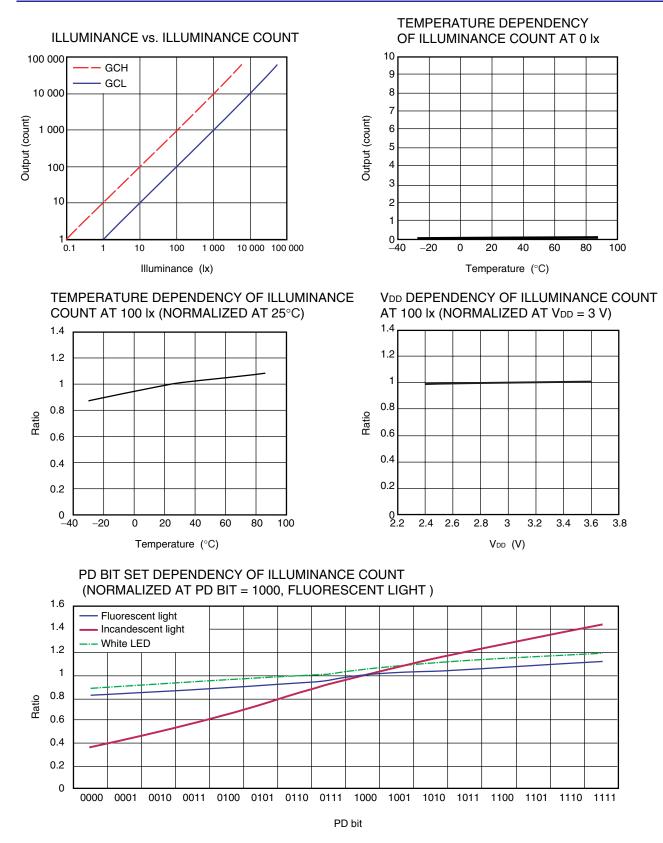


Remark The graphs indicate nominal characteristics.





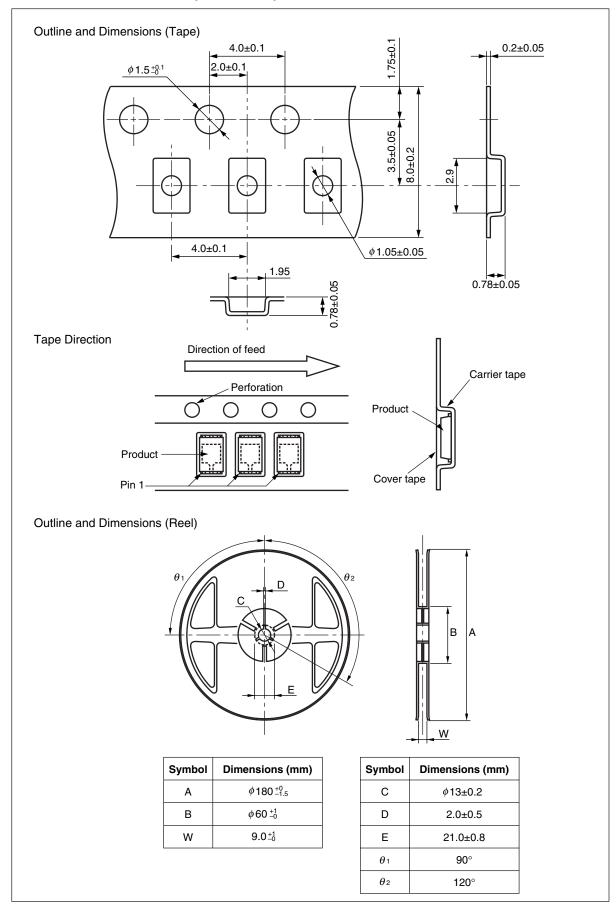






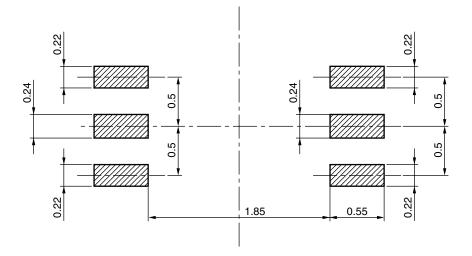


TAPING SPECIFICATIONS (UNIT: mm)





RECOMMENDED MOUNT PAD DIMENSIONS (Unit: mm)



Remark All dimensions in this figure must be evaluated before use.





NOTES ON HANDLING

- 1. Recommended reflow soldering conditions (including infrared reflow, convection reflow, and infrared + convection reflow)
 - (1) This product is dry-packed with desiccant in order to avoid moisture absorption.
 - (2) After breaking the seal, reflow soldering must be done within 168 hours under the recommended temperature profile shown below.
 - (3) If more than 168 hours have passed after breaking the seal, the baking process must be done by using a tape and reel.

Baking conditions: Once, with tape and reel, 60±5°C, 10 to 24 hours

After the baking process, this product must be stored under conditions of 30°C or below, 70% RH or below, and reflow soldering must be done within 168 hours.

<Storage conditions after breaking seal>

- Storage conditions
- Maximum storage period after breaking seal
- : 30°C or below, 70% RH or below

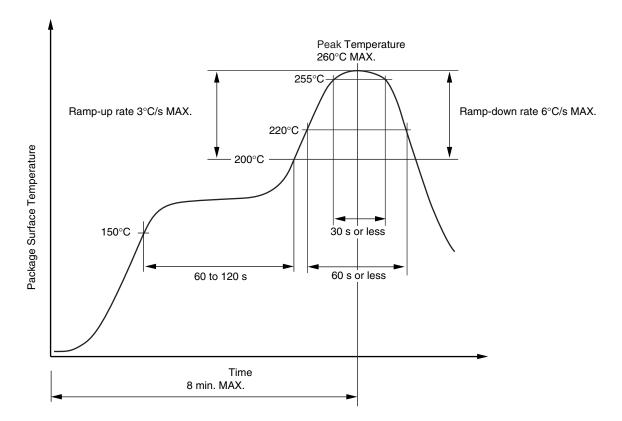
:2

: 168 hours (Second reflow soldering must be completed within 168 hours.)

: 260°C or below (Package surface temperature)

<Reflow soldering conditions>

- Peak reflow temperature
- Maximum number of reflows
- No repair by hand soldering
- Maximum chlorine content of rosin flux (percentage mass) : 0.2% or less



Recommended Temperature Profile of Reflow



Revision History	
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PH5553A2NA1 Data Sheet

				Description			
R	Rev.	Date	Page	Summary			
1	.00	Nov 07, 2012	-	First edition issued			